

# SUMMER SCHOOL

August 1-5, 2011



The University of Tokushima  
Japan



## Sponsors:

1. The University of Tokushima
2. The International Center
3. Center for International Cooperation in Engineering Education (CICEE)
4. FD Committee, Faculty of Engineering
5. Faculty of Integrated Arts and Science

## Introduction

The University of Tokushima is pleased to invite you to participate in the International Summer School which runs from 1 to 5 August, 2011. The Summer School Program was initiated by Center for International Cooperation in Engineering Education (CICEE) to build the understanding and awareness of course subject as well as to increase the knowledge and practical skills.

The prime aim is to provide the platform to young scientists involved in interdisciplinary research and to develop collaborative partnerships on different areas.

## Location

Tokushima city is located in the eastern part of Shikoku island. The population of Tokushima is about 500,000. The Kansai International Airport is located 180 km away from Tokushima. The Tokushima city has connected by bus with the Kansai International Airport (165 min).

## Who can apply

The Summer School is open to the Doctoral students and Master students who are working on Nanotechnology Materials Science; Electrical and Electronic Engineering; Civil and Environmental Engineering, and related topics. Researchers must be affiliated to a university and have a good knowledge of English.

## How to apply

Applicants should submit:

1. A completed application form (found on our website).
2. Few lines about your research topic and the progress you have made in your research.
3. Letter of Motivation (300 words).

Completed application form should be send by an email to [koinkar@cicee.tokushima-u.ac.jp](mailto:koinkar@cicee.tokushima-u.ac.jp)

## Deadline for application

The call for applications closes on **30th May, 2011**. You will be notified by email around 15th June about your acceptance.

## Certificate

All participants registered for Summer School, they will receive an official certificate from The University of Tokushima. The course leads to 2 credits. However, these credits points are recognized depends on each participant's university and Master/PhD program.



## Local Organizing Committee

Prof. Tokuo Ohnishi	(Chair)
Prof. Ri-ichi Murakami	(Vice-Chair)
Dr. Pankaj Koinkar	(Secretary)
Dr. PangPang Wang	(Secretary)
Ms. Sawa Asada	(Assistant)
Ms. Naomi Fujikawa	(Assistant)

## Contact

Center for International Cooperation in Engineering Education (CICEE),  
The University of Tokushima  
2-1 Minamijosanjima Cho,  
Tokushima- 770-8506,  
Japan  
Phone. and Fax : +81-88-656-7643

## Program

The Summer School runs for one week. The Summer School is suitable for Master and PhD students who have decided on a research topic and have already started some research activities. It offers a series of courses taught in English as follows:

### 1. Nanotechnology and Material Science

This course will focus on recent developments in advanced materials and nanotechnology. The basic purpose is to promote and enhance the intensive theoretical and experimental approach to study of various advanced materials and their properties. This course will bring together researchers in the field of Physics, Chemistry, Nanotechnology, Advanced materials, Characterization technique and Synthesis methods. Thus, this course is planned to help participants who are involved in the fundamentals and application of Materials Science and Nanotechnology. In addition, participant will have an opportunity to meet the experts and visit the laboratories.

### 2. Electrical and Electronic Engineering

This course will focus on recent works in electrical and electronic engineering. The topics of this course will be designed as follows: (1) The Basis of Graphene: a new carbon nano-material, (2) Physics and fabrication of photonic semiconductor devices, (3) Semiconductor device and its application, (4) Power electronics for high penetration of renewable energies, (5) Smart power transformer and oil-paper insulation monitoring and diagnostics, (6) Oscillation conditions in circuits and systems, (7) Solving combinatorial optimization problems exploiting neural networks and chaos, and (8) Prognostics and health management of aircraft system. Participants will have an opportunity to meet the experts and visit the laboratories.

### 3. Civil and Environmental Engineering

This course includes a seminar focusing problems of current interest in civil and environmental engineering. Lectures cover recent research topics and developments in wind engineering, concrete /structure engineering, geotechnical engineering, earthquake engineering, urban transport planning and environmental/ecology engineering. The aim of the course is to provide students with in-depth knowledge in the above-mentioned fields and the motivation required for professional development in the postgraduate school of the University of Tokushima. A technical visit to the laboratories of our department and an academic exchange with our master/doctoral course students will also be planned.



### Social Events and Summer School fees

Summer School students will join social events. Social events includes day visit to Akashi bridge, Intercultural party, and sightseeing. Summer School fees amounts to 3000 Yen. The Summer School fee includes the social program and sightseeing. The Summer School fees will be collected at the registration on 1st August.

## Registration form

### Personal information

1. Family name : .....
2. First name : .....
3. Gender:  Male  Female
4. Tel. : .....
5. Fax : .....
6. E-mail : .....
7. Postal address for correspondence :  
.....  
.....
8. Nationality : .....
9. Passport number : .....
10. Date and place of birth :  
.....
11. University : .....
12. Education background :  
 Master  PhD
13. Do you wish to be considered for a Financial assistance toward travel expenses:  
 Yes  No  
If yes then,  Full  Partial
14. Letter of Motivation (300 words):  
(Attached separate sheet)

I declare that the information reported on this form is true and complete

Signature .....

Date : .....